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| AMENDMENT 7            | Docket No.<br>SON-2769 |             |  |          |
|------------------------|------------------------|-------------|--|----------|
| Application No.        | Filing Date            | Examiner    |  | Art Unit |
| 10/603,689-Conf. #2872 | June 26, 2003          | D. C. Davis |  | 1756     |

Applicant(s): Hidetoshi Ohnuma

Invention: EXPOSURE METHOD, MASK FABRICATION METHOD, FABRICATION METHOD OF SEMICONDUCTOR DEVICE AND EXPOSURE APPARATUS

## TO THE COMMISSIONER FOR PATENTS

Transmitted herewith is an amendment in the above-identified application.

The fee has been calculated and is transmitted as shown below.

| CLAIMS AS AMENDED                                                |                                           |                                         |                                   |          |              |                       |  |  |
|------------------------------------------------------------------|-------------------------------------------|-----------------------------------------|-----------------------------------|----------|--------------|-----------------------|--|--|
|                                                                  | Claims<br>Remaining<br>After<br>Amendment | Highest<br>Number<br>Previously<br>Paid | Number<br>Extra Claims<br>Present |          | Rate         |                       |  |  |
| Total Claims                                                     | 12                                        | - 20 =                                  | 0                                 | х        | 50.00        | 0.00                  |  |  |
| Independent<br>Claims                                            | 1                                         | - 3 =                                   | 0                                 | х        | 200.00       | 0.00                  |  |  |
| Multiple Depend                                                  | dent Claims (ch                           | eck if applica                          | ble)                              |          |              |                       |  |  |
| Other fee (pleas                                                 | se specify):                              |                                         |                                   |          |              |                       |  |  |
| TOTAL ADDIT                                                      | 0.00                                      |                                         |                                   |          |              |                       |  |  |
| x Large Entity                                                   |                                           |                                         |                                   |          | Small Entity | /                     |  |  |
| x No additiona                                                   |                                           | d for this am                           | endment.                          | لسسا     |              |                       |  |  |
|                                                                  | ge Deposit Acc                            |                                         |                                   | n the a  | mount of \$  | ·                     |  |  |
| A check in the amount of \$ to cover the filing fee is enclosed. |                                           |                                         |                                   |          |              |                       |  |  |
| Payment by                                                       | credit card. Fo                           | orm PTO-20                              | 88 is attached.                   |          |              |                       |  |  |
|                                                                  | r is hereby auth<br>d below. A dup        |                                         | -                                 | •        |              | No. <u>18-0013</u>    |  |  |
| x Credit a                                                       | ຄy overpaymer                             | nt.                                     |                                   |          |              |                       |  |  |
| X Charge                                                         | any additional fil                        | ing or applica                          | tion processing                   | fees red | quired under | 37 CFR 1.16 and 1.17. |  |  |
| Ronald P./Kan                                                    |                                           |                                         |                                   |          | Dated:       | August 9, 2007        |  |  |
| Attorney/Agent                                                   | Reg. No. 24,                              | 104                                     |                                   |          |              |                       |  |  |
| RADER/ FISHN<br>1233 20th Stree<br>Suite 501                     | et, N.W.                                  | R PLLC                                  |                                   |          |              |                       |  |  |
| WashIngton, D0<br>(202) 955-3750                                 |                                           |                                         |                                   |          |              |                       |  |  |



Docket No.: SON-2769

(PATENT)

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of: Hidetoshi Ohnuma

Thactosin Omiana

Application No.: 10/603,689

Filed: June 26, 2003

For: EXPOSURE METHOD, MASK

FABRICATION METHOD, FABRICATION METHOD OF SEMICONDUCTOR DEVICE

AND EXPOSURE APPARATUS

Confirmation No.: 2872

Art Unit: 1756

Examiner: D. C. Davis

## AMENDMENT AFTER FINAL ACTION UNDER 37 C.F.R. 1.116

MS AF Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Dear Sir:

## **INTRODUCTORY COMMENTS**

In response to the Office Action dated July 11, 2007, please amend the above-identified U.S. patent application as follows:

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks/Arguments begin on page 15 of this paper.